

**IN THE CLAIMS:**

Claims 4, 6-17 and 24-27 were previously cancelled. None of the claims have been amended herein. All of the pending claims are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as previously amended.

**Listing of Claims:**

1. (Previously presented) An interposer, comprising:  
a substrate element; and  
a slot formed through said substrate element, said slot including a first end configured to extend beyond an outer periphery of a semiconductor die upon assembly of the interposer with the semiconductor die and a second end including a laterally recessed area formed in only a portion thereof, wherein said laterally recessed area is positioned for alignment laterally adjacent to a bond pad of the semiconductor die upon positioning the interposer over the semiconductor die, so as to be located laterally over a portion of an active surface of the semiconductor die located between the bond pad and an outer periphery of the semiconductor die.
2. (Previously presented) The interposer of claim 1, wherein said substrate element comprises at least one of a resin, a plastic, silicon, an insulator-coated semiconductor, an insulator-coated material, and an electrically insulative material.
3. (Original) The interposer of claim 1, wherein said laterally recessed area is configured to receive at least a tip of a wire bonding capillary.

Claim 4 (Canceled)

5. (Previously presented) The interposer of claim 1, wherein said laterally recessed area is configured to facilitate access to the bond pad of the semiconductor die by equipment for forming, positioning, or securing intermediate conductive elements.

Claims 6-17 (Canceled)

18. (Previously presented) A semiconductor device assembly, comprising:  
a semiconductor die with a plurality of bond pads on an active surface thereof, at least one bond pad of said plurality of bond pads being located adjacent an outer periphery of said semiconductor die; and  
an interposer positionable over said semiconductor die, said interposer including at least one elongate slot formed therethrough, said at least one elongate slot including an end with a laterally recessed area formed in a portion thereof, said laterally recessed area, upon positioning said interposer over said semiconductor die, exposing said at least one bond pad and at least a portion of said active surface located between said at least one bond pad and said outer periphery of said semiconductor die.

19. (Previously presented) The semiconductor device assembly of claim 18, wherein said plurality of bond pads of said semiconductor die is arranged substantially linearly across a central region of said active surface.

20. (Original) The semiconductor device assembly of claim 18, wherein said laterally recessed area is configured to receive at least a portion of apparatus for forming, positioning, or securing an intermediate conductive element.

21. (Original) The semiconductor device assembly of claim 18, wherein said laterally recessed area is configured to receive at least a tip of a wire bonding capillary so as to facilitate electrical connection of said at least one bond pad to a corresponding contact pad on a surface of said interposer.

22. (Original) The semiconductor device assembly of claim 18, further comprising an intermediate conductive element extending between said at least one bond pad and a corresponding contact area on said interposer.

23. (Previously presented) The semiconductor device assembly of claim 18, wherein said interposer is part of a strip comprising a plurality of physically connected interposers, each interposer of said plurality being configured for assembly with a corresponding semiconductor die.

Claims 24-27 (Canceled)

28. (Previously presented) An interposer, comprising:  
a substrate element; and  
a slot formed through said substrate element, said slot including a first end configured to extend beyond an outer periphery of a semiconductor die upon assembly of the interposer with the semiconductor die and a second end including a laterally recessed area formed in only a portion thereof and configured to facilitate access to a bond pad of the semiconductor die by equipment for forming, positioning, or securing an intermediate conductive element such that an end of the intermediate conductive element is secured to or located adjacent to the bond pad.

29. (Previously presented) The interposer of claim 28, wherein said substrate element comprises at least one of a resin, a plastic, silicon, an insulator-coated semiconductor, an insulator-coated material, and an electrically insulative material.

30. (Previously presented) The interposer of claim 28, wherein said laterally recessed area is configured to receive at least a tip of a wire bonding capillary.

31. (Previously presented) The interposer of claim 28, wherein said laterally recessed area is positioned for alignment laterally adjacent to the bond pad of the semiconductor die upon positioning the interposer over the semiconductor die, so as to be located laterally over a portion of an active surface of the semiconductor die located between the bond pad and an outer periphery of the semiconductor die.

32. (Previously presented) A semiconductor device assembly, comprising:  
a semiconductor die with a plurality of bond pads on an active surface thereof, at least one bond pad of said plurality of bond pads being located adjacent an outer periphery of said semiconductor die; and  
an interposer positionable over said semiconductor die, said interposer including at least one elongate slot formed therethrough, said at least one elongate slot including an end with a laterally recessed area formed in a portion thereof, said laterally recessed area:  
upon positioning said interposer over said semiconductor die, exposing said at least one bond pad and at least a portion of said active surface located between said at least one bond pad and said outer periphery of said semiconductor die; and  
configured to receive at least a portion of apparatus for forming, positioning, or securing an intermediate conductive element.

33. (Previously presented) The semiconductor device assembly of claim 32, wherein said plurality of bond pads of said semiconductor die is arranged substantially linearly across a central region of said active surface.

34. (Previously presented) The semiconductor device assembly of claim 32, further comprising an intermediate conductive element extending between said at least one bond pad and a corresponding contact area on said interposer.

35. (Previously presented) The semiconductor device assembly of claim 32, wherein said interposer is part of a strip comprising a plurality of physically connected interposers, each interposer of said plurality being configured for assembly with a corresponding semiconductor die.